NOTE:
1. DRAWING IS NOT A JEDEC PACKAGE OUTLINE
2. DRAWING NOT TO SCALE
3. ALL DIMENSIONS ARE IN MILLIMETERS
4. DIMENSIONS OF EXPOSED PAD ON BOTTOM OF PACKAGE DO NOT INCLUDE MOLD FLASH, MOLD FLASH, IF PRESENT, SHALL NOT EXCEED 0.20mm ON ANY SIDE
5. EXPOSED PAD SHALL BE SOLDER PLATED
6. SHADED AREA IS ONLY A REFERENCE FOR PIN 1 LOCATION ON THE TOP AND BOTTOM OF PACKAGE

UHG Package
52-Lead Plastic QFN (5mm x 8mm)
(Reference LTC DWG # 05-08-1507 Rev Ø)

PACKAGE OUTLINE

RECOMMENDED SOLDER PAD PITCH AND DIMENSIONS
APPLY SOLDER MASK TO AREAS THAT ARE NOT SOLDERED

PIN 1 NOTCH
R = 0.30 TYP OR
0.35 × 45° CHAMFER

PIN 1 TOP MARK
(SEE NOTE 6)

TOP VIEW—EXPOSED PAD

BOTTOM VIEW—EXPOSED PAD

0.10 ± 0.05